

Errata

SLAZ052J-May 2009-Revised November 2011

CC430F613x, CC430F612x, CC430F513x Device Erratasheet

1 Current Version

See Appendix A for prior silicon revisions.

✓ The checkmark means that the issue is present in the specified revision.

Devices	Rev:	ADC24	ADC25	ADC27	ADC29	COMP4	CPU18	CPU20	CPU24	CPU25	CPU26	CPU27	CPU28	CPU29	CPU30	CPU31	CPU32	CPU33	CPU34	CPU35	CPU39	CPU40	DMA4
CC430F5133	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	√	✓
CC430F5135	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	√	✓
CC430F5137	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	√	✓
CC430F6125	Е					✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6126	Е					✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6127	Е					✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6135	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6137	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓

Devices	Rev:	DMA7	DMA8	EEM8	EEM9	EEM11	EEM13	EEM14	EEM16	EEM17	FLASH29	FLASH31	FLASH37	JTAG20	JTAG21	.CDB1	срвз	.CDB4	MPY1	PMAP1	PMM8	РММ9	PMM10
				ш _	ш	ш		ш _	ш _	ш	<u>.</u>		<u>.</u>	-	7	_	_	_	_	<u>.</u>			
CC430F5133	Е	√	√	√	✓	✓	✓	√	√	✓	√	✓	✓	✓	✓				✓	✓	✓	✓	✓
CC430F5135	E	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓				✓	✓	✓	✓	✓
CC430F5137	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓				✓	✓	✓	✓	✓
CC430F6125	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6126	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6127	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6135	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6137	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓



Package Markings www.ti.com

Devices	Rev:	PMM11	PMM12	PMM14	PMM15	PMM17	PORT15	RF1A1	RF1A2	RF1A3	RF1A5	RF1A6	RF1A8	RTC4	SYS16	TAB23	9SON	UCS7	0CS9	UCS10	USC126	USCI30	WDG4
CC430F5133	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F5135	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F5137	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6125	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6126	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6127	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6135	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
CC430F6137	Е	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓

2 Package Markings

RGC64 QFN (RGC), 64 pin

	TI	= TI
CC430Fxxxx	YM	= Year and Month Date Code
CC4301 XXXX	LLLI	L = LOT Trace Code
TI YMS #	S	= Assembly Site Code
LLLL G4	#	= DIE Revision
LLLL <u>04</u>	O	= PIN 1

RGZ48 QFN (RGZ), 48 Pin

	TI	= TI
CC430	YM	= Year and Month Date Code
Fxxxx		L = LOT Trace Code
	S	= Assembly Site Code
TI YMS #	#	= DIE Revision
LLLL <u>G4</u>	0	= PIN 1

3 Detailed Bug Description

ADC24 ADC12 Module

Function Unexpected ADC12 current draw when ADC12ENC = 1

Description When set, the ADC12ENC bit issues a clock request to the selected source clock, even

before the conversion trigger. This causes some extra current consumption, depending

on the selected clock.

Workaround None

ADC25 ADC12 Module

Function Write to ADC12CTL0 triggers ADC12 when CONSEQ = 00

Description If ADC conversions are triggered by the Timer_B module and the ADC12 is in

single-channel single-conversion mode (CONSEQ = 00), ADC sampling is enabled by write access to any bit(s) in the ADC12CTL0 register. This is contrary to the expected behavior that only the ADC12 enable conversion bit (ADC12ENC) triggers a new ADC12

sample.

Workaround When operating the ADC12 in CONSEQ = 00 and a Timer_B output is selected as the

sample and hold source, temporarily clear the ADC12ENC bit before writing to other bits in the ADC12CTL0 register. The following capture trigger can then be re-enabled by

setting ADC12ENC = 1.

ADC27

ADC12 Module

Function

Integral and differential non-linearity exceed specifications

Description

The ADC12_A integral and differential non-linearity may exceed the limits specified in the data sheet under the following conditions:

- If the internal voltage reference generator is used and
- If the reference voltage is not buffered off-chip and
- If f_{ADC12CLK} > 2.7 MHz or

If the internal voltage reference is selected for 1.5-V output mode.

The non-linearity can be up to tens of LSBs. This is due to the internal reference buffer providing insufficient drive for the switched capacitor array of the ADC12_A.

Workaround

- Turn on the output of the internal voltage reference to increase the drive strength of the reference to the ADC_12 core:
 - If REFMSTR bit in REFCTL0 is 0 (allowing Shared REF to be controlled by ADC_A reference control bits)

Set ADC12REFON bit in ADC12CTL0 = 1 and

Set ADC12REFOUT bit in ADC12CTL2 = 1

If REFMSTR bit in REFCTL0 is 1

Set REFON and REFOUT bits in REFCTL0 = 1

or

 Ensure f_{ADC12CLK} < 2.7 MHz and select the internal voltage reference in 2.5-V output mode.

Depending on the frequency of the source of $f_{ADC12CLK}$ (ACLK, MCLK, SMCLK, or MODOSC), select the divider bits accordingly.

- If f_{ADC12CLK} = MODOSC (ADC12OSC)

ADC12CTL1 |= ADC12DIV_2; // Divide clock by 2 If $f_{ADC12CLK} = ACLK/SMCLK/MCLK > 2.7 MHz$

Use ADC12DIVx and/or ADC12PDIVx bits to reduce the selected clock frequency to between 0.45 MHz and 2.7 MHz.

And set both REFVSELx bits in REFCTL0 to REFVSEL_3 (select 2.5-V output).

ADC29 ADC12 Module

Function

Incorrect temperature sensor calibration data

Description

In some devices, the internal temperature sensor calibration data for 30°C are invalid for all V_{Ref} conditions. Devices with correct calibration data show a difference of at least 30 LSBs between the different V_{Ref} conditions. When using incorrect calibration data with the internal temperature sensor ADC samples, the calculated results can be unreliable. Calibration data for 85°C are not affected.

This erratum only affects devices with Lot Trace Code dated prior to 01/2011.

Workaround

Recalibrate the temperature sensor for 30°C at the application level.

COMP4 Comparator_B Module

Function CBEX and CBOUTPOL bits do not invert comparator I/O

DescriptionSetting the exchange bit, CBEX, does not interchange the comparator inputs. Similarly setting the output polarity bit, CBOUTPOL, does not invert the output of the comparator.

Workaround To obtain an inverted output from the comparator, invert the input signals to the comparator using the channel input selector bits, CBIPSEL x and CBIMSEL x. Make

sure to use a MOV instruction so that the inputs are inverted simultaneously.

CPU18 CPU Module

Function LPM instruction can corrupt PC/SR registers

Description The PC and SR registers have the potential to be corrupted when:

 An instruction using register, absolute, indexed, indirect, indirect auto-increment, or symbolic mode is used to set the LPM bits (e.g., BIS &xyh, SR).

and

This instruction is followed by a CALL or CALLA instruction.

Upon servicing an interrupt service routine, the program counter (PC) is pushed twice onto the stack instead of the correct operation where the PC, then the SR registers are pushed onto the stack. This corrupts the SR and possibly the PC on RETI from the ISR.

Workaround Insert a NOP or __no_operation() intrinsic function between the instruction to enter low-power mode and the CALL or CALLA instruction.

CPU20 CPU Module

Function

Description

An unexpected Vacant Memory Access Flag (VMAIFG) can be triggered due to the CPU autoincrement of the MAB+2 outside the range of a valid memory block.

The VMAIFG can be triggered under the following conditions:

 If an interrupt is requested, fetched by the CPU, but lost before execution of the interrupt service routine.

0

2. If a PC-modifying instruction (for example, RET, PUSH, CALL, POP, JMP, BR) is fetched from the last address of a section of memory (Flash or RAM) that is not contiguous to a higher valid section on the memory map.

Workaround For case 1 – None

For case 2 – If code is affected, edit the linker command file to make the last four bytes of affected memory sections unavailable.

Detailed Bug Description

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CPU24

CPU Module

Function

Program counter corruption following entry into low-power mode

Description

The program counter is corrupted when an interrupt event occurs in the time between (and including) one cycle before and one cycle after the CPUOFF bit is set in the status register. This failure occurs when the BIS instruction is followed by a CALL or CALLA instruction using the following addressing modes:

BIS &, SR

CALLA indir, indir autoinc, reg

BIS INDEX. SR

CALLA indir, indir autoinc, reg

BIS reg, SR

CALLA reg, indir, indir autoinc

NOTE: Due to the instruction emulation, the EINT instruction, as well as the _enable_interrupts() and possibly the __bis_SR_register() intrinsic functions are affected.

Workaround

Insert a NOP instruction or no operation() intrinsic function call between the BIS and CALL or CALLA instructions.

CPU25

CPU Module

Function

DMA transfer does not execute during low-power mode

Description

If the following instruction sequence is used ([] denotes an addressing mode) to enter a low-power mode, and the DMARMWDIS bit is set, then DMA transfers are blocked for the duration of the low-power mode.

BIS [registerlindex|absolute|symbolic].SR

CALLA [register]

Workaround

Insert a NOP instruction or __no_operation() intrinsic function call between the BIS and CALLA instructions

Temporarily disable the DMARMWDIS bit when entering low-power mode.

CPU₂₆

CPU Module

Function

CALL SP does not behave as expected

Description

When the intention is to execute code from the stack, a CALL SP instruction skips the first piece of data (instruction) on the stack. The second piece of data at SP + 2 is used as the first executable instruction.

Workaround

Write the op code for a NOP as the first instruction on the stack. Begin the intended subroutine at address SP + 2.

CPU27 CPU Module

Function Program Counter (PC) is corrupted during the context save of a nested interrupt

Description

When a low-power mode is entered within an interrupt service routine that has enabled nested interrupts (by setting the GIE bit), and the instruction that sets the low-power mode is directly followed by a RETI instruction, an incorrect value of PC + 2 is pushed to

the stack during the context save. Hence, the RETI instruction is not executed on return from the nested interrupt, and the PC becomes corrupted.

from the nested interrupt, and the PC becomes corrupted.

Workaround Insert a NOP or __no_operation() intrinsic function between the instruction that sets the

lower power mode and the RETI instruction.

CPU28 CPU Module

Function PC is corrupted when using certain extended addressing mode combinations

DescriptionAn extended memory instruction that modifies the program counter executes incorrectly when preceded by an extended memory write-back instruction under the following

conditions:

First instruction:

2-operand instruction, extended mode using (register,index), (register,absolute), or

(register,symbolic) addressing modes

Second instruction:

2-operand instruction, extended mode using the (indirect,PC), (indirect

auto-increment,PC), or (indexed [with ind 0], PC) addressing modes

Example BISX.A R6,&AABCD ANDX.A @R4+,PC

Workaround

Insert a NOP or a __no_operation() intrinsic function between the two instructions.

Do not use an extended memory instruction to modify the PC.

Detailed Bug Description

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CPU29

CPU Module

Function

Using a certain instruction sequence to enter low-power mode(s) affects the instruction width of the first instruction in an NMI ISR

Description

If there is a pending NMI request when the CPU enters a low-power mode (LPMx) using an instruction of Indexed source addressing mode, and that instruction is followed by a 20-bit wide instruction of Register source and Destination addressing modes, the first instruction of the ISR is executed as a 20-bit wide instruction.

Example

```
main:
                [indexed],SR
        MOV.W
                                       ; Enter LPMx
        MOVX.A [register],[register] ; 20-bit wide instruction
     ISR_start:
        MOV.B
                [indexed],[register] ; ERROR - Executed as a 20-bit
instruction!
```

Note: [] indicates addressing mode

Workaround

Insert a NOP or a no operation() intrinsic function following the instruction that enters the LPMx using indexed addressing mode.

- Use a NOP or a no operation() intrinsic function as first instruction in the ISR.
- Do not use the indexed mode to enter LPMx.

CPU₃₀

CPUX Module

Function

ADDA, SUBA, CMPA [immediate], PC behave as if immediate value were offset by -2

Description

The extended address instructions ADDA, SUBA, and CMPA in immediate addressing mode are represented by 4 bytes of opcode (see the MSP430F5xx Family User's Guide (SLAU208) for more details). In cases where the program counter (PC) is used as the destination register, only 2 bytes of the current instruction's 4-byte opcode are accounted for in the PC value. The resulting operation executes as if the immediate value were offset by a value of -2.

Example

Ideal: ADDA #Immediate-4, PC ...is equivalent to...

Actual: ADDA #Immediate-2, PC

NOTE: The MOV instruction is not affected.

Workaround

- Modify immediate value in software to account for the offset of 2.
- Use extended 20-bit instructions (addx.a, subx.a, cmpx.a) instead.

CPU31 **CPUX Module**

SP corruption **Function**

Description When the instruction PUSHX.A is executed using the indirect auto-increment mode with

the stack pointer (SP) as the source register [PUSHX.A @SP+], the SP is consequently corrupted. Instead of decrementing the value of the SP by four, the value of the SP is replaced with the data pointed to by the SP previous to the PUSHX.A instruction

execution.

Workaround None. The compiler does not generate a PUSHX.A instruction that involves the SP.

CPU32 **CPUX Module**

CALLA PC executes incorrectly **Function**

When the instruction CALLA PC is executed, the program counter (PC) that is pushed Description

onto the stack during the context save is incorrectly offset by a value of -2.

Workaround None. The compiler does not generate a CALLA PC instruction.

CPU33 **CPUX Module**

Function CALLA [indexed] may corrupt the program counter

When the Stack Pointer (SP) is used as the destination register in the CALLA Description

index(Rdst) instruction and is preceded by a PUSH or PUSHX instruction in any of the following addressing modes: Absolute, Symbolic, Indexed, Indirect register, or Indirect auto-increment, the "index" of the CALLA instruction is not sign extended to 20-bits and is always treated as a positive value. This causes the Program Counter to be set to a wrong address location when the index of the CALLA instruction represents a negative

offset.

NOTE: This erratum applies only when the instruction sequence is: PUSH or PUSHX followed by CALLA index(SP).

This erratum does not apply if the PUSH or PUSHX instruction is used in the Register or Immediate addressing mode.

This erratum applies only when SP is used as the destination register in

the CALLA index(Rdst) instruction.

Place a NOP instruction in between the PUSH or PUSHX and the CALLA index(SP) instructions.

NOTE: This bug has no compiler impact as the compiler does not generate a

CALLA instruction that uses indexed addressing mode with the SP.

Workaround

CPU34 CPU Module

Function CPU may be halted if a conditional jump is followed by a rotate PC instruction

DescriptionIf a conditional jump instruction (JZ, JNZ, JC, JNC, JN, JGE, JL) is followed by an Address Rotate instruction on the PC (RRCM, RRAM, RRUM) and the jump is

not performed, the CPU is halted.

Workaround Insert a NOP between the conditional jump and the rotate PC instructions.

CPU35 CPU Module

Function Instruction BIT.B @Rx,PC uses the wrong PC value

Description The BIT(.B/.W) instruction in indirect register addressing mode is represented by 2 bytes

of opcode. And if Program Counter (PC) is used as the destination register, the 2 opcode bytes of the current BIT instruction are not accounted for. The resulting operation executes the instruction using the wrong PC value, and this affects the results in the

Status Register (SR).

Workaround None

NOTE: The compiler does not generate a BIT instruction that uses the PC as an

operand.

CPU39 CPU Module

Function PC is corrupted when single-stepping through an instruction that clears the GIE bit

Description Single-stepping over an instruction that clears the General Interrupt Enable bit (for

example, DINT or BIC #GIE, SR) when the GIE bit was previously set may corrupt the PC. For example, DINT or BIC #GIE, SR is a 2-byte instruction. Single stepping through this instruction increments the PC by a value of 4 instead of 2, thus corrupting the next

PC value.

NOTE: This erratum applies to debug mode only.

Workaround Insert a NOP or __no_operation() intrinsic immediately after the line of code that clears

the GIE bit.

CPU40

CPU Module

Function

PC is corrupted when executing jump/conditional jump instruction that is followed by instruction with PC as destination register or a data section

Description

If the value at the memory location immediately following a jump/conditional jump instruction is 0X40h or 0X50h (where X = don't care), which could either be an instruction opcode (for instructions like RRCM, RRAM, RLAM, RRUM) with PC as destination register or a data section (const data in flash memory or data variable in RAM), then the PC value is auto-incremented by 2 after the jump instruction is executed; therefore, branching to a wrong address location in code and leading to wrong program execution.

For example, a conditional jump instruction followed by data section (0140h).

@0x8012 Loop DEC.W R6
@0x8014 DEC.W R7
@0x8016 JNZ Loop
@0x8018 Value1 DW 0140h

Workaround

In assembly, insert a NOP between the jump/conditional jump instruction and program code with instruction that contains PC as destination register or the data section.

DMA4

DMA Module

Function

Corrupted write access to 20-bit DMA registers

Description

When a 20-bit wide write to a DMA address register (DMAxSA or DMAxDA) is interrupted by a DMA transfer, the register contents may be unpredictable.

Workaround

 Design the application to ensure that no DMA access interrupts 20-bit wide accesses to the DMA address registers.

or

- When accessing the DMA address registers, enable the Read Modify Write disable bit (DMARMWDIS = 1), or temporarily disable all active DMA channels (DMAEN = 0).
- Use word access for accessing the DMA address registers. Note that this limits the values that can be written to the address registers to 16-bit values (lower 64K of flash).

DMA7

DMA Module

Function

DMA interrupt lost

Description

If a DMA request is received during the time when the read address of a read modify write instruction is on the Memory Address Bus (MAB), application interrupts could be lost.

Workaround

Set the DMARMWDIS bit when using the DMA.

Detailed Bug Description

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DMA8 DMA Module

Function DMA can corrupt values on write-access to program stack

Description If the DMA controller makes a write access to the stack while executing one of the

following instructions, the data that is written may be corrupted.

CALLA [REG | IDX | SYM | ABS | IND | INA | IMM] PUSHX.A [IDX | SYM | ABS | IND | IMM | INA]

PUSHX.A [REG] PUSHM.A [REG] POPM.A [REG]

Note: [] denotes an addressing mode

Workaround Do not declare function-scope variables. Declare all variables that are intended to be modified by the DMA as global- or file-scope such that they are allocated in the data

section of RAM and not on the program stack.

EEM8 **Enhanced Emulation Module**

Function Debugger stops responding when using the DMA

> In repeated transfer mode, the DMA automatically reloads the size counter (DMAxSZ) once a transfer is complete and immediately continues to execute the next transfer unless the DMA Enable bit (DMAEN) has been previously cleared. In burst-block transfer mode, DMA block transfers are interleaved with CPU activity 80/20% - of ten CPU cycles, eight are allocated to a block transfer and two are allocated for the CPU.

Because the JTAG system must wait for the CPU bus to be clear to halt the device, it can only do so when two conditions are met:

- Three clock cycles after any DMA transfer, the DMA is no longer requesting the bus.
- The CPU is not requesting the bus.

Therefore, if the DMA is configured to operate in the repeat burst-block transfer mode, and a breakpoint is set between the line of code that triggers the DMA transfers and the line that clears the DMAEN bit, the DMA always requests the bus and the JTAG system never gains control of the device.

When operating the DMA in repeat burst-block transfer mode, set breakpoint(s) only when the DMA transfers are not active (before the start or after the end of the DMA

transfers).

Enhanced Emulation Module

When the PUSH instruction is used in any addressing mode except register or Description

Combined triggers on the PUSH instruction may be missed

immediate modes, a combined trigger may be missed when its conditions are defined by a PUSH instruction fetch and a successful match of the value being pushed onto stack.

Workaround None

Workaround

EEM9

Function

Description

EEM11 Enhanced Emulation Module

Function Condition register write trigger fails while executing rotate instructions

Description A conditional register write trigger will fail to generate the expected breakpoint if the

trigger condition is a result of executing one of the following rotate instructions: RRUM,

RRCM, RRAM and RLAM.

Workaround None

NOTE: This erratum applies to debug mode only.

EEM13 Enhanced Emulation Module

Function Halting the debugger does not return correct PC value when in LPM

Description When debugging, if the device is in any low-power mode and the debugger is halted, the

program counter update by the debugger is corrupted. The debugger is unable to halt at

the correct location.

Workaround None

NOTE: This erratum applies to debug mode only.

EEM14 Enhanced Emulation Module

Function Single-step or breakpoint on module register with WAIT capability may not work

Description In debug mode, the CPU clock is driven independently from the wait inputs of device

modules (i.e., MULT, USB, RF1A, CRC). As a result, an EEM halt on an access to the module data registers (breakpoint or single-step) may show incorrect results due to

incomplete execution.

Workaround Do not single-step through a data register access that holds the CPU to provide a valid

result. Place breakpoints after the affected register is accessed and sufficient clock

cycles have been provided.

NOTE: This erratum applies to debug mode only.

EEM16 Enhanced Emulation Module

Function The state storage display does not work reliably when used on instructions with CPU

Wait cycles.

Description When executing instructions that require wait states; the state storage window updates

incorrectly. For example a flash erase instruction causes the CPU to be held until the erase is completed i.e. the flash puts the CPU in a wait state. During this time if the state storage window is enabled it may incorrectly display any previously executed instruction

multiple times.

NOTE: This erratum affects debug mode only.

Workaround Do not enable the state storage display when executing instructions that require wait

states. Instead set a breakpoint after the instruction is completed to view the state

storage display.

EEM17 Enhanced Emulation Module

Function Wrong Breakpoint halt after executing Flash Erase/Write instructions

Description Hardware breakpoints or Conditional Address triggered breakpoints on instructions that

follow Flash Erase/Write instructions, stops the debugger at the actual Flash Erase/Write instruction even though the flash erase/write operation has already been executed. The hardware/conditional address triggered breakpoints that are placed on either the next two single opcode instructions OR the next double opcode instruction that follows the

Flash Erase/Write instruction are affected by this erratum.

NOTE: This erratum affects debug mode only.

Workaround None. Use other conditional/advanced triggered breakpoints to halt the debugger right

after Flash erase/write instructions.

FLASH29 Flash Module

Function Read disturb due to emergency exit from write/erase Flash operation

Description When a Flash write or erase is abruptly terminated, any further reliable reads from Flash

are not ensured. The abrupt termination can occur as a result of the Emergency Exit bit (EMEX in FCTL3) being set. This forces a write or an erase operation to be terminated

before normal completion.

Workaround After setting EMEX = 1, wait for at least 100 µs after a bank or mass erase and at least

6 µs after a segment erase before Flash is accessed again.

FLASH31 Flash Module

Function Interrupts not disabled during flash operation

Description When a flash operation is in progress, interrupts are not automatically disabled. The

CPU will always attempt to service the interrupt request, whether or not the flash is busy.

Workaround Disable interrupts using the GIE bit before erasing flash in another bank of memory.

Note that all interrupts during this period of time remain pending until GIE = 1.



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FLASH37

Flash Module

Function

Corrupted flash read when SVM low-side flag is triggered

Description

If the SVM low side is enabled, a change in the VCORE voltage level (an increase in the VCORE level) may cause the currently executed read operation from flash to be incorrect and may lead to unexpected code execution or incorrect data. This can happen under any one of the following conditions:

- When the VCORE is changed in the application, the SVM low side is used to indicate
 if the core voltage has settled by using the SVMDLYIFG flag. The failure occurs only
 when a flash access is concurrent with the expiration of the settling time delay.
- · Unexpected changes in the VCORE voltage level

For code examples and detailed guidance on the PMM operation, see the application report MSP430F5xx and MSP430F6xx Core Libraries (SLAA448).

Workaround

- Execute the procedure to change the VCORE level from RAM.
- If executing from flash, follow the procedure below when increasing the VCORE level. Note: To apply this workaround, the SVM low-side comparator must operate in normal mode (SVMLFP = 0 in SVMLCTL).

```
// Set SVM highside to new level and check if a VCore increase is possible
 SVSMHCTL = SVMHE | SVSHE | (SVSMHRRL0 * level);
 // Wait until SVM highside is settled
 while ((PMMIFG & SVSMHDLYIFG) == 0);
 // Clear flag
 PMMIFG &= ~SVSMHDLYIFG;
 // Set also SVS highside to new level
 // Vcc is high enough for a Vcore increase
 SVSMHCTL |= (SVSHRVL0 * level);
 // Wait until SVM highside is settled
 while ((PMMIFG & SVSMHDLYIFG) == 0);
 // Clear flag
 PMMIFG &= ~SVSMHDLYIFG;
 //**********flow change for errata workaround ********
 // Set VCore to new level
 PMMCTLO_L = PMMCOREVO * level;
 // Set SVM, SVS low side to new level
 SVSMLCTL = SVMLE | (SVSMLRRL0 * level)| SVSLE | (SVSLRVL0 * level);
 // Wait until SVM, SVS low side is settled
 while ((PMMIFG & SVSMLDLYIFG) == 0);
 // Clear flag
 PMMIFG &= ~SVSMLDLYIFG;
 //***********flow change for errata workaround ********
```

JTAG20

JTAG Module

Function

BSL does not exit to application code

Description

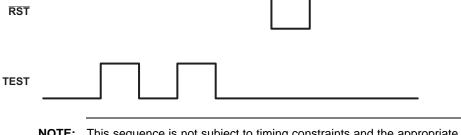
The methods used to exit the BSL per MSP430 Programming Via the Bootstrap Loader (SLAU319) are invalid.

Workaround

To exit the BSL one of the following methods must be used.

A power cycle

Toggle the TEST pin twice when RST is high, and then pull RST low.



NOTE: This sequence is not subject to timing constraints and the appropriate level transitions are sufficient to trigger an exit from BSL mode.

JTAG21

JTAG Module

Function

"Attach to Running Target" resets device

Description

The "attach to running target" feature in IAR occasionally resets the device before

getting it under JTAG control.

Workaround

Use alternative methods (for example, outputting device status/variables via port pins or UART) to debug unattached running target.

LCDB1

LCD B Module

Function

VLCDEXT bit not working properly

Description

When the VLCDEXT bit is set an external voltage applied to the LCDCAP/R33 pin should serve as the LCD voltage. This works as expected when the V2 to V4 voltages are generated externally (LCDEXTBIAS = 1) and external resistors are connected on the R03 to R33 resistor ladder. If internal V2 to V4 bias voltage generation is selected (LCDEXTBIAS = 0), applying an external LCD voltage on LCDCAP VLCDEXT has no effect.

Workaround

The expected behavior for the VLCDEXT bit can be achieved by setting the VLCDx bits to a non-zero value and leaving the charge pump disabled (LCDCPEN = 0). The VLCDx bits are don't care when the charge pump is disabled so this does not result in any additional or unexpected current consumption.

LCDB3 LCD_B Module

Function LCDFRMIFG set erroneously when LCDON changed from 1 to 0

Description The LCD_B frame interrupt flag (LCDFRMIFG) can be set erroneously when the

interrupt is enabled ((LCDFRMIE = 1) and the LCD_B module is switched off (LCDON

changed from 1 to 0).

Workaround Disable the frame interrupt before switching off the LCD_B module.

LCDB4 LCD B Module

Function Write access to LCDBIV does not reset LCD IFGs

Description A write access to the LCDBIV register does not automatically reset all pending interrupt

flags.

Workaround Clear all interrupt flags in software by writing 0 to the lowest nibble of LCDBCTL1, where

the flags are stored.

MPY1 Hardware Multiplier (MPY) Module

Function Save and Restore feature on MPY32 not functional

Description The MPY32 module uses the Save and Restore method which involves saving the

multiplier state by pushing the MPY configuration/operand values to the stack before using the multiplier inside an Interrupt Service Routine (ISR) and then restoring the state by popping the configuration/operand values back to the MPY registers at the end of the ISR. However due to the erratum the Save and Restore operation fails causing the write operation to the OP2H register right after the restore operation to be ignored as it is not

preceded by a write to OP2L register resulting in an invalid multiply operation.

NOTE: When using the C-compiler, the interrupts are automatically disabled

None. Disable interrupts when writing to OP2L and OP2H registers.

while using the MPY32.

PMAP1 Port Mapping Controller

Function Port Mapping Controller does not clear unselected inputs to mapped module

Description The Port Mapping Controller provides the logical OR of all port mapped inputs to a

module (Timer, USCI, etc). If the PSEL bit (PxSEL.y) of a port mapped input is cleared, then the logic level of that port mapped input is latched to the current logic level of the input. If the input is in a logical high state, then this high state is latched into the input of the logical OR. In this case, the input to the module is always a logical 1 regardless of

the state of the selected input.

Workaround

Workaround

 Drive input to the low state before clearing the PSEL bit of that input and switching to another input source.

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• Use the Port Mapping Controller reconfiguration feature, PMAPRECFG, to select inputs to a module and map only one input at a time.

PMM8 Power Management Module

Function Supply current in LPM4.5 is unpredictable

Description Due to an unpredictable value of the supply current in LPM4.5, the mode should not be

used.

Workaround None

PMM9 Power Management Module

Function False SVSxIFG events

The comparators of the SVS require a certain amount of time to stabilize and output a correct result once re-enabled; this time is different for the Full Performance versus the Normal mode. The time to stabilize the SVS comparators is intended to be accounted for by a built-in event-masking delay of 2 µs when Full Performance mode is enabled.

However, the comparators of the SVS in Full Performance mode take longer than 2 µs to stabilize, so the possibility exists that a false positive will be triggered on the SVSH or SVSL. This results in the SVSxIFG flags being set and, depending on the configuration of SVSxPE bit, a POR can also be triggered .

Additionally, when the SVSxIFGs are set, all GPIOs are three-state; that is, floating until the SVSx comparators are settled.

The SVS IFGs are falsely set under the following conditions:

- 1. Wakeup from LPM2/3/4 when SVSxMD = 0 (default setting) and SVSxFP = 1. The SVSx comparators are disabled automatically in LPM2/3/4 and are then re-enabled on return to active mode.
- 2. SVSx is turned on in full performance mode (SVSxFP = 1).
- 3. A PUC/POR occurs after SVSx is disabled. After a PUC or POR, the SVSx are enabled automatically, but the settling delay is not triggered. Based on the SVSxPE bit, this may lead to POR events until the SVS comparator is fully settled.

Workaround

Description

For each of the above listed conditions the following workarounds apply:

- 1. If the Full Performance mode is to be enabled for either the high-side or low-side SVS comparators, the respective SVSxMD bits must be set (SVSxMD = 1) such that the SVS comparators are not temporarily shut off in LPM2/3/4. Note that this is equivalent to a 2 μ A (typical) adder to the low-power mode current, per the device-specific data sheet, for each SVSx that remains enabled.
- 2. The SVSx must be turned on in normal mode (SVSxFP = 0). It can be reconfigured to use full performance mode once the SVSx/SVMx delay has expired.
- 3. Ensure that SVSH and SVSL are always enabled.

PMM10 Power Management Module

Function SVS/SVM flags disabled after Power Up Clear reset

DescriptionSVS/SVM interrupt flags are not set after a Power Up Clear (PUC) Reset if the SVS was

disabled before the PUC reset was applied.

Workaround A write access to the intended SVSx register after PUC re-enables the SVS and SVM interrupt flags.

PMM11

Power Management Module

Function

MCLK comes up fast on exit from LPM3 and LPM4

Description

The DCO exceeds the programmed frequency of operation on exit from LPM3 and LPM4 for a period of time up to 6 μ s. This behavior is masked from affecting code execution by default: SVSL and SVML run in normal-performance mode and mask CPU execution for 150 μ s on wakeup from LPM3 and LPM4. However, when the low-side SVS and the SVM are disabled or operating in full-performance mode (that is, SVMLE = 0, SVSLE = 0, or SVMLFP = 1, SVSLFP = 1) and MCLK is sourced from the internal DCO running over 4 MHz, 7 MHz, 11 MHz, or 14 MHz at core voltage levels 0, 1, 2, or 3, respectively, the mask lasts only 2 μ s. MCLK is, therefore, susceptible to run out of spec for 4 μ s.

Workaround

Set the MCLK divide bits in the Unified Clock System Control 5 Register (UCSCTL5) to divide MCLK by two prior to entering LPM3 or LPM4 (set DIVMx = 001). This prevents MCLK from running out of spec when the CPU wakes from the low power mode. Following the wakeup from the low power mode, wait 32, 48, 80, or 100 cycles for core voltage levels 0, 1, 2, or 3, respectively, before resetting DIVMx to zero and running MCLK at full speed [for example, __delay_cycles(100)].

PMM12

Power Management Module

Function

SMCLK comes up fast on exit from LPM3 and LPM4

Description

The DCO exceeds the programmed frequency of operation on exit from LPM3 and LPM4 for a period of time up to 6 µs. When SMCLK is sourced by the DCO, it is not masked on exit from LPM3 or LPM4. Therefore, SMCLK exceeds the programmed frequency of operation on exit from LPM3 and LPM4 for up to 6 µs. The increased frequency has the potential to change the expected timing behavior of peripherals that select SMCLK as the clock source.

Workaround

- Use XT2 as the SMCLK oscillator source instead of the DCO.
 or
- Do not disable the clock request bit for SMCLKREQEN in the Unified Clock System Control 8 Register (UCSCTL8). This means that all modules that depend on SMCLK to operate successfully should be halted or disabled before entering LPM3 or LPM4. If the increased frequency prevents the proper function of an affected module, wait 32, 48, 80, or 100 cycles for core voltage levels 0, 1, 2, or 3, respectively, before re-enabling the module [for example, __delay_cycles(100)].

PMM14

Power Management Module

Function

Increasing the core level when SVS/SVM low side is configured in full-performance mode causes device reset

Description

When the SVS/SVM low side is configured in full performance mode (SVSMLCTL.SVSLFP = 1), the settling time delay for the SVS comparators is approximately 2 μ s. When increasing the core level in full-performance mode; the core voltage does not settle to the new level before the settling time delay of the SVS/SVM comparator expires. This results in a device reset.

Workaround

When increasing the core level, enable the SVSSV/M low side in normal mode (SVSMLCTL.SVSLFP = 0). This provides a settling time delay of approximately 150 μ s, allowing the core sufficient time to increase to the expected voltage before the delay expires.





PMM15

Power Management Module (SVxH and SVxL)

Function

Device may not wake up from LPM2, LPM3, or LPM4

Description

Device may not wake up from LPM2, LPM3, or LPM4 if an interrupt occurs within 1 μ s after entry to the specified LPMx; entry can be caused either by user code or automatically (for example, after a previous ISR is completed). Device can be recovered with an external reset or a power cycle. Additionally, a PUC can also be used to reset the failing condition and bring the device back to normal operation (for example, a PUC caused by the WDT).

This effect is seen when:

 A write to the SVSMHCTL and SVSMLCTL registers is immediately followed by an LPM2, LPM3, or LPM4 entry without waiting the requisite settling time (PMMIFG.SVSMLDLYIFG = 0 and PMMIFG.SVSMHDLYIFG = 0).

or

- · The following two conditions are met:
 - The SVSL/SVML module is configured for a fast wake-up or the SVSL/SVML module is turned off. The affected SVSMLCTL register settings are shaded in the following table.

	SVSLE	SVSLMD	SVSLFP	AM, LPM0/1 SVSL state	Manual SVSMLACE = 0 LPM2/3/4 SVSL State	Automatic SVSMLACE = 1 LPM2/3/4 SVSL State	Wakeup Time LPM2/3/4
SVSL	0	Х	Х	OFF	OFF	OFF	twake-up fast
	1	0	0	Normal	OFF	OFF	twake-up slow
	1	0	1	Full Performance	OFF	OFF	twake-up fast
	1	1	0	Normal	Normal	OFF	twake-up slow
	1	1	1	Full Performance	Full Performance	Nomal	twake-up fast
	SVMLE	SVM	II FP	AM, LPM0/1	Manual SVSMLACE = 0	Automatic SVSMLACE = 1	Wakeup Time
SVML	OVIIILL	0411		SVML state	LPM2/3/4 SVML State	LPM2/3/4 SVML State	LPM2/3/4
	0	>	(OFF	OFF	OFF	t _{WAKE-UP FAST}
	1	()	Normal	Normal	OFF	t _{WAKE-UP} SLOW
	1	1		Full Performance	Full Performance	Nomal	t _{WAKE-UP FAST}

and

 The SVSH/SVMH module is configured to transition from Normal mode to an OFF state when moving from Active/LPM0/LPM1 into LPM2/LPM3/LPM4 modes. The affected SVSMHCTL register settings are shaded in the following table.

	SVSHE	SVSHMD	SVSHFP	AM, LPM0/1	Manual SVSMHACE = 0	Manual SVSMHACE = 1
	SVOIL	SVSIIIVID	3 4 31 11 1	SVSH state	LPM2/3/4	LPM2/3/4
					SVSH State	SVSH State
SVSH	0	х	Х	OFF	OFF	OFF
	1	0	0	Normal	OFF	OFF
	1	0	1	Full Performance	OFF	OFF
	1	1	0	Normal	Normal	OFF
	1	1	1	Full Performance	Full Performance	Normal
					Manual	Manual
	SVSHE	SVM	LED	AM, LPM0/1	SVSMHACE = 0	SVSMHACE = 1
	SVSHE	SVIVI	пгг	SVSH state	LPM2/3/4	LPM2/3/4
SVMH					SVSH State	SVSH State
	0	Х	(OFF	OFF	OFF
	1	C)	Normal	Normal	OFF
	1	1		Full Performance	Full Performance	Normal



Workaround

Any write to the SVSMxCTL register must be followed by a settling delay (PMMIFG.SVSMLDLYIFG = 0 and PMMIFG.SVSMHDLYIFG = 0) before entering LPM2, LPM3, or LPM4.

and

or

- 1. Make sure that the SVSx and SVMx are configured to prevent the issue from occurring by the following:
 - Configure the SVSL module for slow wake up (SVSLFP = 0). Note that this increases the wakeup time from LPM2, LPM3, or LPM4 to $t_{\text{WAKE-UP SLOW}}$ (approximately 150 μ s).

 Do not configure the SVSH and SVMH such that the modules transition from Normal mode to an OFF state on LPM entry. Instead, force the modules to remain ON even in LPMx. Note that this causes increased power consumption when in LPMx.

See the MSP430F5xx and MSP430F6xx Core Libraries (SLAA448) for proper PMM configuration functions.

Use the following function, PMM15Check (void), to determine whether or not the existing PMM configuration is affected by the erratum. The return value of the function is 1 if the configuration is affected, and 0 if the configuration is not affected.

2. If fast servicing of interrupts is required, add a 150-µs delay in either the interrupt service routine or before entry into LPM3/LPM4.

Detailed Bug Description

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PMM17

Power Management Module (SVxH and SVxL)

Function

V_{CORF} exceeds maximum limit of 2.0 V

Description

If a device switches between active mode and LPM2/3/4 with very high frequency, the core voltage of the device, V_{CORE}, may rise incrementally until it is beyond 2.0 V, which is the maximum allowable limit for digital circuitry internal to the MSP430. This increase may remain undetected in an application with no functional impact, but it could potentially result in decreased endurance and increased wear over the lifetime of the device, because the digital circuitry is continually subjected to overvoltage.

The accumulation of V_{CORE} affects only older lot trace codes of the silicon revisions specified in the table at the beginning of this appendix.

Workaround

The V_{CORF} accumulation is fixed by enabling a prolongation mechanism in software. The following lines of code must be implemented before periodic execution of LPM-to-AM-to-LPM. It is recommended to execute the code at program start:

ASM code:

```
mov.w #0x9602, &0110h;
bis.w #0x0800, &0112h;
```

C code:

(unsigned int)(0x0110)=0x9602; *(unsigned int*)(0x0112) = 0x0800;

The automatic prolongation mechanism is disabled with a BOR and must be enabled after each boot code execution.

For detailed background information, affected LTCs, and possible workaround(s) see Core Voltage Accumulation (SLAA505).

PORT15

Digital I/O Module, Port 1 and 2

Function

In-system debugging causes the PMALOCKED bit to be always set

Description

The port mapping controller registers cannot be modified when single-stepping or halting at break points between a valid password write to the PMAPWD register and the expected lock of the port mapping (PMAP) registers. This causes the PMAPLOCKED bit to remain set and not clear as expected.

NOTE: This erratum only applies to in-system debugging and is not applicable when operating in free-running mode.

Workaround

Do not single step through or place break points in the port mapping configuration section of code.



RF1A1

RF1A Module

Function

The PLL lock detector output is not 100% reliable

Description

The PLL lock detector output is not 100% reliable and might toggle even if the PLL is in lock. The PLL is in lock if the lock detector output has a positive transition or is constantly logic high. The PLL is not in lock if the lock detector output is constantly logic low. It is not recommended to check for PLL lock by reading PKTSTATUS[0] with GDOx_CFG = 0x0A or PKTSTATUS[2] register with GDOx_CFG = 0x0A (x = 0 or 2).

Workaround

PLL lock can be checked reliably by these methods:

- Program register IOCFGx.GDOx_CFG = 0x0A and use the lock detector output available on the GDOx pin as an interrupt for the MCU. A positive transition on the GDOx pin means that the PLL is in lock. It is important to disable for interrupt when waking the chip from SLEEP state as the wake-up might cause the GDOx pin to toggle when it is programmed to output the lock detector.
- Read register FSCAL1. The PLL is in lock if the register content is different from 0x3F.

With both of the above workarounds the CC1101 PLL calibration should be carried out with the correct settings for TEST0. VCO_SEL_CAL_EN and FSCAL2.VCO_CORE_H_EN. These settings are depending on the operating frequency and are calculated automatically by SmartRF® Studio.

Note that the TEST0 register content is not retained in SLEEP state, and thus it is necessary to write to this register as described here when returning from the SLEEP state.

RF1A2

RF1A Module

Function

RXFIFO overflow flag does not work as intended

Description

In addition to having a 64-byte long RX FIFO, the CC430 has a one byte long pre-fetch buffer between the FIFO and the RF1A module. It also has buffers for status registers and CRC bytes. If more than 65 bytes have been received (the FIFO and the pre-fetch buffer are full) without reading the RX FIFO, the radio will enter RXFIFO_OVERFLOW state. There are, however, some cases where the radio will be stuck in RX state instead of entering RXFIFO_OVERFLOW state. Below is a table showing the register settings that will cause this problem. APPEND_STATUS is found in the PKTCTRL1 register, and CRC_EN is found in the PKTCTRL0 register.

Setting IOCFGx=0x06 should mean that the GDO signal is deasserted when the RXFIFO overflows. In the cases where the radio is stuck in RX state, the GDOx pin will not be deasserted.

When the radio is stuck in this RX state it draws current as if it was in the RX state, but it will not be able to receive any more data. The only way to get out of this state is to issue an SIDLE strobe and then flush the FIFO (SFRX).

Workaround

In applications where the packets are short enough to fit in the RX FIFO and one wants to wait for the whole packet to be received before starting to read the RX FIFO, for variable packet length mode (PKTCTRL0.LENGTH_CONFIG=1) the PKTLEN register should be set to 61 to make sure the whole packet including status bytes are 64 bytes or less (length byte (61) + 61 payload bytes + 2 status bytes = 64 bytes) or PKTLEN = 62 if fixed packet length mode is used (PKTCTRL0.LENGTH_CONFIG=0). In application where the packets do not fit in the RX FIFO, one must start reading the RX FIFO before it reaches its limit (64 bytes).

RF1A3 RF1A Module

Function Extra Byte Transmitted in TX

Description If transmission is aborted (exits TX mode) during the transmission of the first half of any

byte, there is a repetition of the first byte in the next transmission. This issue is caused by a state machine controlling the mod_rd_data signal in the modulator. This signal asserts at the start of transmission of each full byte, then deasserts after half the byte has been transmitted. If the transmission is aborted after a byte has started but before half the byte is transmitted, this signal remains asserted and the first byte in the next

transmission is repeated.

Workaround As long as the packet handling features of the CC430 are used, this is not a problem

because the chip always exits TX mode after the transmission of the last bit in the last byte of the packet. If, however, the packet handling features are disabled

(MDMCFG2.SYNC_MODE=0) and TX mode is manually exited by strobing IDLE, ensure that the IDLE strobe is being issued after clocking out 12 dummy bits (8 dummy bits are necessary due to the TX latency, but because this would mean that transmission is

aborted within the first half of a byte, 4 extra bits are added).

RF1A5 RF1A Module

Function FIFO Radio Core Interrupt may be triggered independent of the RFINx condition being

met

Description The radio core interrupt flags (RFIFGx) may be set and could generate a radio core

interrupt although the corresponding radio input (RFINx) signal condition has not been

met.

This is true for the FIFO Mapped Control Signals RFIFG3, RFIFG4, RFIFG5, RFIFG6,

RFIFG7, RFIFG8, RFIFG9 (negative edge), and RFIFG10 (negative edge).

Workaround When handling the radio core interrupts RFIFG3 to RFIFG10, proceed with the ISR only

after verifying that the RFINx signal respective to the RFIFGx flag is active.

RF1A6 RF1A Module

Function LVERR flag set when radio in SLEEP or IDLE and VCORE = 0 or 1

Description The low-voltage error flag (LVERR) is set when the radio is in the SLEEP or IDLE state

and VCORE = 0 or 1, which is contrary to the behavior specified in the CC430 User's

Guide.

Workaround None

RF1A8 RF1A Module

Function RF1AIN10 bit does not reset after the first byte of the RX FIFO is read

Description The intended behavior of the RF1AIN10 bit is that it is set when the last byte is received

(into the RX FIFO) and reset when the first byte is read from the RX FIFO. However, the

RF1AIN10 bit does not reset after the first byte of the RX FIFO is read.

Workaround Use RF1AIN9 for RX handling instead. To verify the RX packet CRC, enable the RF1A

option to append the CRC_OK bit to the end of the RX packet. The CRC_OK bit can be

checked after reading out the RX FIFO buffer.

RTC4 RTC Module

Function RTC clock calibration maybe offset by +2 ppm

Description When using the RTC clock calibration feature, the RTCCLK frequency maybe offset by

+2 ppm after the calibration procedure is completed. This affects both up and down

calibration.

Workaround None

SYS16 System Module

Function Fast V_{CC} ramp after device power up may cause a reset

Description At initial power-up, after V_{CC} crosses the bownout threshold and reaches a constant

level, an abrupt ramp of V_{cc} at a rate $dV/dT > 1V/100\mu s$ can cause a brownout condition to be incorrectly detected even though V_{cc} does not fall below the brownout threshold.

This causes the device to undergo a reset.

Workaround Use a controlled V_{CC} ramp to power the device.

TAB23 Timer_A/Timer_B Module

Function TAXR read can be corrupted when TAXR = TAXCCR0

Description When a timer in Up mode is stopped and the counter register (TAxR) is equal to the

TAxCCR0 value, a read of the TAR register may return an unexpected result.

Workaround

Use Up/Down mode instead of Up mode.

or

• In Up mode, use the timer interrupt instead of halting the counter and reading out the

value in TAxR.

or

· When halting the timer counter in 'Up' mode, reinitialize the timer before starting to

run again.

UCS6 Universal Clock System Module

Function USCI source clock does not turn off in LPM3/4 when UART is idle

Description The USCI clock source (ACLK/SMCLK) remains enabled in LPM3 and LPM4 when the

USCI is configured in UART mode and the communication is idle (UCSWRST = 0 but no TX or RX currently executing). This is contrary to the expected automatic clock activation described in the user's guide and can lead to higher current consumption in low-power

modes, depending on the oscillator that feeds ACLK/SMCLK.

Workaround Use the oscillator that is already active in LPM3 (ACLK) to source the USCI and use the

low-power baud rate generator (UCOS16 = 0). For UART baud rates where a fast SMCLK sourced by the internal DCO is required, use LPM0 instead of LPM3.

Detailed Bug Description

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UCS7

Universal Clock System Module

Function

DCO drifts when servicing short ISRs when in LPM0 or exiting active from ISRs for short periods of time

Description

The FLL uses two rising edges of the reference clock to compare against the DCO frequency and decide on the required modifications to the DCOx and MODx bits. If the device is in a low-power mode with FLL disabled (LPM0 with DCO not sourcing ACLK/SMCLK or LPM2, LPM3, LPM4 where SCG1 bit is set) and enters a state that enables FLL (enter ISR from LPM0/LPM2 or exit active from ISRs) for a period less than three reference clock cycles, then the FLL will cause the DCO to drift.

This occurs because the FLL immediately begins comparing an active DCO with its reference clock and making the respective modifications to the DCOx and MODx bits. If the FLL is not given sufficient time to capture a full reference clock cycle (two reference clock periods) and adjust accordingly (one reference clock period), then the DCO keeps drifting each time the FLL is enabled.

Workaround

- If DCO is not sourcing ACLK or SMCLK in the application, use LPM1 instead of LPM0 to make sure FLL is disabled when interrupt service routine is serviced.
- When exiting active from ISRs, insert a delay of at least three reference clock periods. To save on power budget, the three reference clock periods could also be spent in LPM0 with TimerA or TimerB using ACLK/SMCLK sourced from DCO. This way, the FLL and DCO are still active in LPM0.

UCS9

Universal Clock System Module

Function

Digital Bypass mode prevents entry into LPM4

Description

When entering LPM4, if an external digital input applied to XT1 in HF mode or XT2 is not turned off, the PMM does not switch to low-current mode causing higher than expected power consumption.

Workaround

Before entering LPM4:

- Switch to a clock source other than external bypass digital input or
- Turn off external bypass mode (UCSCTL6.XT1BYPASS = 0)

UCS10

Universal Clock System Module

Function

Modulation causes shift in DCO frequency

Description

When the FLL is enabled, the DCO frequency can be tracked automatically by modifying the DCOx and MODx bits. The MODx bits switch between the frequency selected by the DCO bits and the next higher frequency set by (DCO + 1). The erroneous behavior is seen when the FLL is tracking close to a DCO step boundary and the MOD counter is expected to rollover but, instead, the DCO bits increment and the MOD bits decrement. This causes the DCO to shift by up to 12% and remain at an increased frequency until approximately 15 REFCLK cycles have elapsed. The frequency reverts to the expected value immediately afterward.

For example, the modulator moves from DCOx = n and MODx = 31 to DCOx = n + 1 and MODx = 30, causing a large increase in the DCO frequency.

Applications could be impacted as follows:

 When using the DCO frequency for asynchronous serial communication and timer operation, the effect can be seen as corrupted data or incorrect timing events.

Workaround

- Change the clock source from the DCO to an external crystal oscillator (for example, XT1 or XT2, if available on the device) during the critical timing phase.
 - or
- Implement a software FLL, comparing the DCO frequency to a known reference such as REFO or LFXT1 using a timer capture and tuning the value of the DCO and MOD bits periodically.

or

- Execute the following sequence in periodic intervals.
 - 1. Disable peripherals sourced by the DCO such as UART and timer.
 - 2. Turn on the FLL.
 - 3. Wait the worst case settling time of $32 \times 32 \times f_{FLLREFCLK}$ to allow the FLL to lock to the target frequency.
 - 4. Turn off the FLL.
 - 5. Compare the DCO frequency to a known reference such as REFO or LFXT1 using a timer capture.
 - If the DCO frequency is higher than expected, repeat from step (2) until the frequency reaches the expected range.
 - Else proceed with code execution.

See the application report *UCS10 Guidance* (<u>SLAA489</u>) for information regarding working with this erratum. This erratum does not affect proper operation of the CPU when MCLK = DCO/FLL and is set to the maximum clock frequency specified in the device-specific data sheet.



USCI26 USCI Module

Function t_{buf} parameter violation in I²C multi-master mode

Description In multi-master I^2C systems, the timing parameter t_{buf} (bus free time between a stop condition and the following start) is not ensured to match the I^2C specification of 4.7 μ s

in standard mode and 1.3 µs in fast mode. If the UCTXSTT bit is set during a running I²C transaction, the USCI module waits and issues the start condition on bus release,

causing the violation to occur.

NOTE: It is recommended to check if UCBBUSY bit is cleared before setting

UCTXSTT = 1.

Workaround None

USCI30

USCI Module

Function

I2C mode master receiver / slave receiver

Description

The USCI I2C module, when configured as a receiver (master or slave), performs a double-buffered receive operation. For example, in a transaction of two bytes, after the first byte is moved from the receive shift register to the receive buffer, the byte is acknowledged and the state machine allows the reception of the next byte.

If the receive buffer has not been cleared of its contents by reading the UCBxRXBUF register by the time the seventh bit of the following data byte is received, an error condition may occur on the I2C bus. Depending on the USCI configuration, the following may occur:

- If the USCI is configured as an I2C master receiver, an unintentional repeated start condition can be triggered or the master can switch into an idle state (I2C communication aborted). The reception of the current data byte is not successful in this case.
- If the USCI is configured as I2C slave receiver, the slave can switch to an idle state, stalling I2C communication. The reception of the current data byte is not successful in this case. The USCI I2C state machine notifies the master of the aborted reception with a NACK.

Note that the error condition described above occurs only within a limited window of the seventh bit of the current byte being received. If the receive buffer is read outside of this window (before or after), then the error condition does not occur.

Workaround

The error condition can be avoided by servicing the UCBxRXIFG in a timely manner. This can be done by (a) servicing the interrupt and ensuring UCBxRXBUF is read promptly or (b) using the DMA to automatically read bytes from receive buffer upon UCBxRXIFG being set.

OR

If the receive buffer cannot be read out in time, test the I2C clock line before the UCBxRXBUF is read out to ensure that the critical window has elapsed. This is done by checking if the clock line low status indicator bit UCSCLLOW is set for at least three USCI bit clock cycles; that is, $3 \times t_{BitClock}$.

NOTE: The last byte of the transaction must be read directly from UCBxRXBUF. For all other bytes, follow the workaround.

Code flow for workaround:

- 1. Enter RX ISR for reading receiving bytes
- 2. Check if UCSCLLOW.UCBxSTAT == 1
- 3. If no, repeat step 2 until set.
- 4. If yes, repeat step 2 for a time period > $3 \times t_{BitClock}$, where $t_{BitClock} = 1/f_{BitClock}$
- 5. If window of 3 × t_{BitClock} cycles has elapsed, it is safe to read UCBxRXBUF.



WDG4 Watchdog Module

Function The WDT failsafe can be disabled

Description The UCS is capable of masking clock requests (ACLK, SMCLK, MCLK) from peripheral

modules; see request enable (REQEN) bits in the UCS control register, UCSCTL8.

The clock request logic of the UCS is used by the WDT module to ensure a fail-safe clock source in all low-power modes. Therefore, de-asserting the request enable bit of the watchdog clock source (xCLKREQEN = 0) allows the respective clock to be disabled upon entry into a low-power mode. Without an active clock source, the WDT timer stops

incrementing and a watchdog event does not occur.

Workaround None



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Appendix A Prior Revisions

None



Revision History www.ti.com

Revision History

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NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

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